



STH90N15F4-2 STP90N15F4

N-channel 150 V, 12.5 mΩ, 95 A TO-220, H²PAK
STripFET™ DeepGATE™ Power MOSFET

Preliminary data

Features

Type	V _{DSS}	R _{DS(on)} max	I _D
STH90N15F4-2	150 V	< 15.6 mΩ	95 A
STP90N15F4	150 V	< 16 mΩ	90 A

- Extremely low on-resistance R_{DS(on)}
- 100% avalanche tested

Application

- Switching applications

Description

This STripFET™ DeepGATE™ Power MOSFET technology is among the latest improvements, which have been especially tailored to minimize on-state resistance, with a new gate structure, providing superior switching performance.

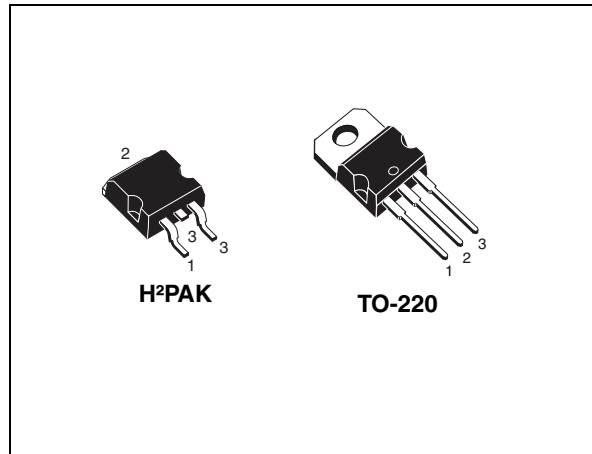
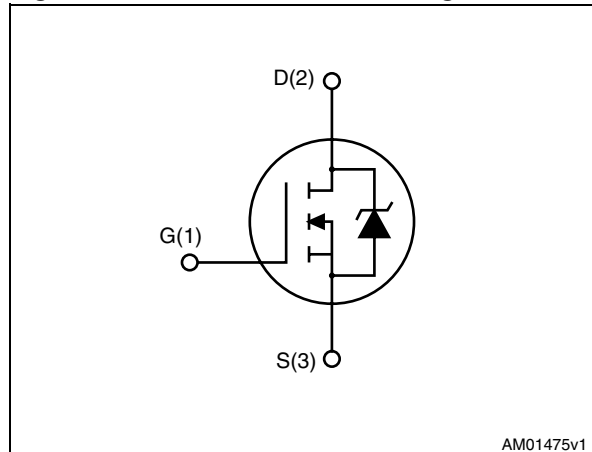


Figure 1. Internal schematic diagram



AM01475v1

Table 1. Device summary

Order codes	Marking	Package	Packaging
STH90N15F4-2	90N15F4	H ² PAK	Tape and reel
STP90N15F4	90N15F4	TO-220	Tube

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
3	Test circuits	6
4	Package mechanical data	7
5	Revision history	11

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-220	H ² PAK	
V _{DS}	Drain-source voltage (V _{GS} = 0)	150		V
V _{GS}	Gate-source voltage	± 20		V
I _D	Drain current (continuous) at T _C = 25 °C	90	95	A
I _D	Drain current (continuous) at T _C = 100 °C	65	66	A
I _{DM} ⁽¹⁾	Drain current (pulsed)	360	380	A
P _{TOT}	Total dissipation at T _C = 25 °C	315		W
	Derating factor	2.1		W/°C
E _{AS} ⁽²⁾	Single pulse avalanche energy	TBD		mJ
T _{stg}	Storage temperature	- 55 to 175		°C
T _j	Max. operating junction temperature			

1. Pulse width limited by safe operating area
2. Starting T_j = 25 °C, I_D = 50 A, V_{DD} = 60 V

Table 3. Thermal data

Symbol	Parameter	Value		Unit
		TO-220	H ² PAK	
R _{thj-case}	Thermal resistance junction-case max	0.48		°C/W
R _{thj-pcb}	Thermal resistance junction-pcb max		35 ⁽¹⁾	°C/W
R _{thj-a}	Thermal resistance junction-ambient max	62.5		°C/W
T _l	Maximum lead temperature for soldering purpose	300		°C

1. When mounted on 1inch² FR-4 board, 2 oz Cu.

2 Electrical characteristics

($T_{CASE} = 25\text{ °C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown voltage	$I_D = 250\ \mu\text{A}$, $V_{GS} = 0$	150			V
I_{DSS}	Zero gate voltage Drain current ($V_{GS} = 0$)	$V_{DS} = \text{max rating}$ $V_{DS} = \text{max rating}$, $T_C = 125\text{ °C}$			1 100	μA μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 20\text{ V}$			100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\ \mu\text{A}$	2		4	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$, $I_D = 45\text{ A}$ ⁽¹⁾		13	16	m Ω
		$V_{GS} = 10\text{ V}$, $I_D = 45\text{ A}$ ⁽²⁾		12.5	15.6	m Ω

1. for TO-220

2. for H²PAK

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit		
C_{iss}	Input capacitance			10.4		nF		
C_{oss}	Output capacitance	$V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0$	-	750	-	pF		
C_{rss}	Reverse transfer capacitance						288	pF
Q_g	Total gate charge	$V_{DD} = 80\text{ V}$, $I_D = 90\text{ A}$, $V_{GS} = 10\text{ V}$ <i>(see Figure 3)</i>	-	175	-	nC		
Q_{gs}	Gate-source charge						TBD	nC
Q_{gd}	Gate-drain charge						TBD	nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on delay time	$V_{DD} = 75\text{ V}$, $I_D = 45\text{ A}$ $R_G = 4.7\ \Omega$, $V_{GS} = 10\text{ V}$ <i>(see Figure 2)</i>	-	TBD	-	ns
	Rise time					
$t_{d(off)}$ t_f	Turn-off-delay time	$V_{DD} = 75\text{ V}$, $I_D = 45\text{ A}$, $R_G = 4.7\ \Omega$, $V_{GS} = 10\text{ V}$ <i>(see Figure 2)</i>	-	TBD	-	ns
	Fall time					

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
I_{SD}	Source-drain current	TO-220	-		90	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		360	A
I_{SD}	Source-drain current	H ² PAK	-		95	A
$I_{SDM}^{(2)}$	Source-drain current (pulsed)		-		380	A
$V_{SD}^{(3)}$	Forward on voltage	$I_{SD} = 90\text{ A}, V_{GS} = 0$	-		TBD	V
t_{rr}	Reverse recovery time	$I_{SD} = 90\text{ A}, V_{DD} = 25\text{ V}$ $di/dt = 100\text{ A}/\mu\text{s},$ $T_J = 150\text{ }^\circ\text{C}$ <i>(see Figure 4)</i>	-	TBD		ns
Q_{rr}	Reverse recovery charge			TBD		nC
I_{RRM}	Reverse recovery current			TBD		A

1. Pulse width limited by safe operating area.
2. Pulse width limited by safe operating area.
3. Pulsed: Pulse duration = 300 μs , duty cycle 1.5%

3 Test circuits

Figure 2. Switching times test circuit for resistive load

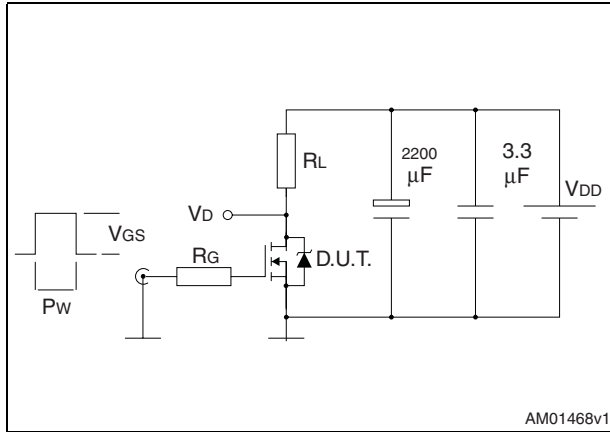


Figure 3. Gate charge test circuit

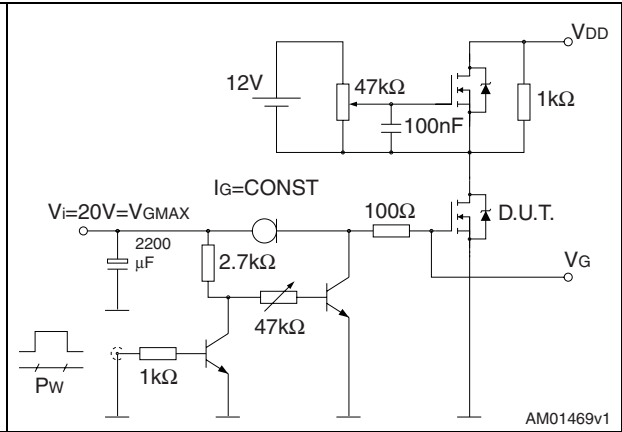


Figure 4. Test circuit for inductive load switching and diode recovery times

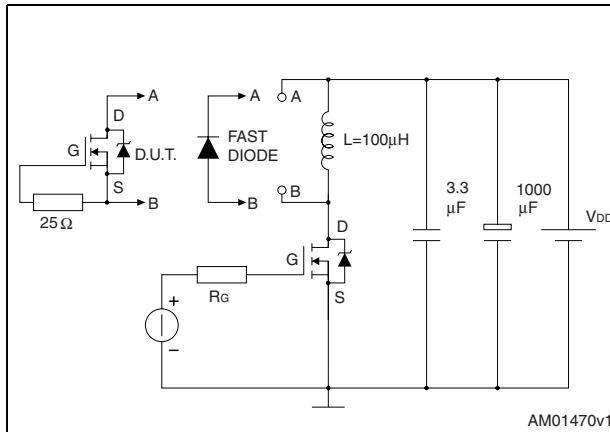


Figure 5. Unclamped inductive load test circuit

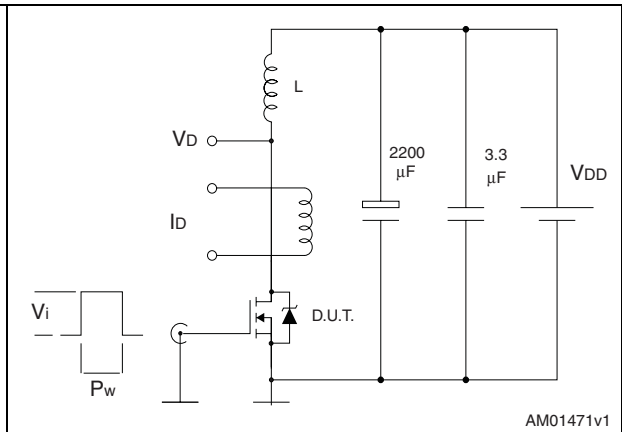


Figure 6. Unclamped inductive waveform

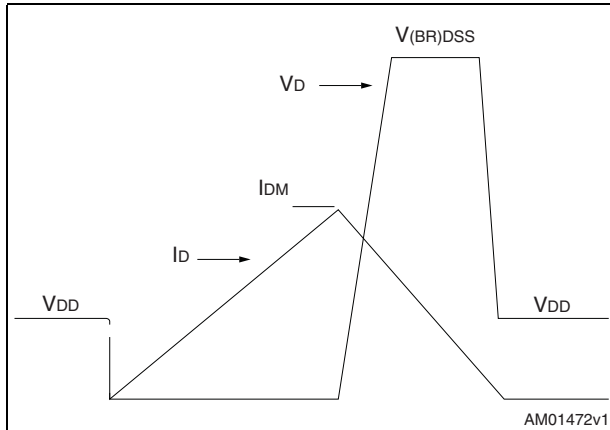
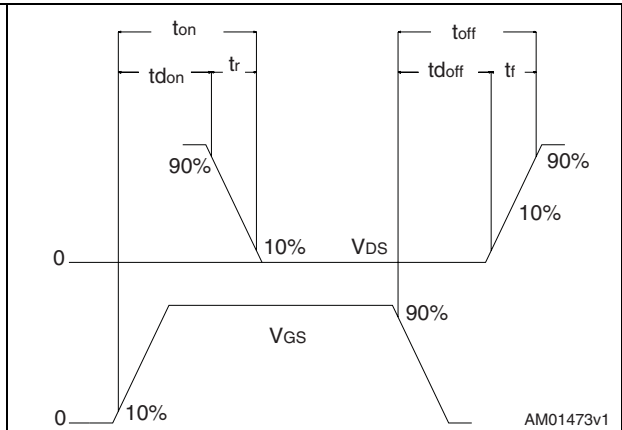


Figure 7. Switching time waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 8. H²PAK 2 leads mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.30		4.80
A1	0.03		0.20
C	1.17		1.37
e	4.98		5.18
E	0.50		0.90
F	0.78		0.85
H	10.00		10.40
H1	7.171		7.971
L	15.30		15.80
L1	1.27		1.40
L2	4.93		5.23
L3	7.45		7.85
L4	1.5		1.7
M	2.6		2.9
R	0.20		0.60
V	0°		8°

Figure 8. H²PAK 2 leads drawing

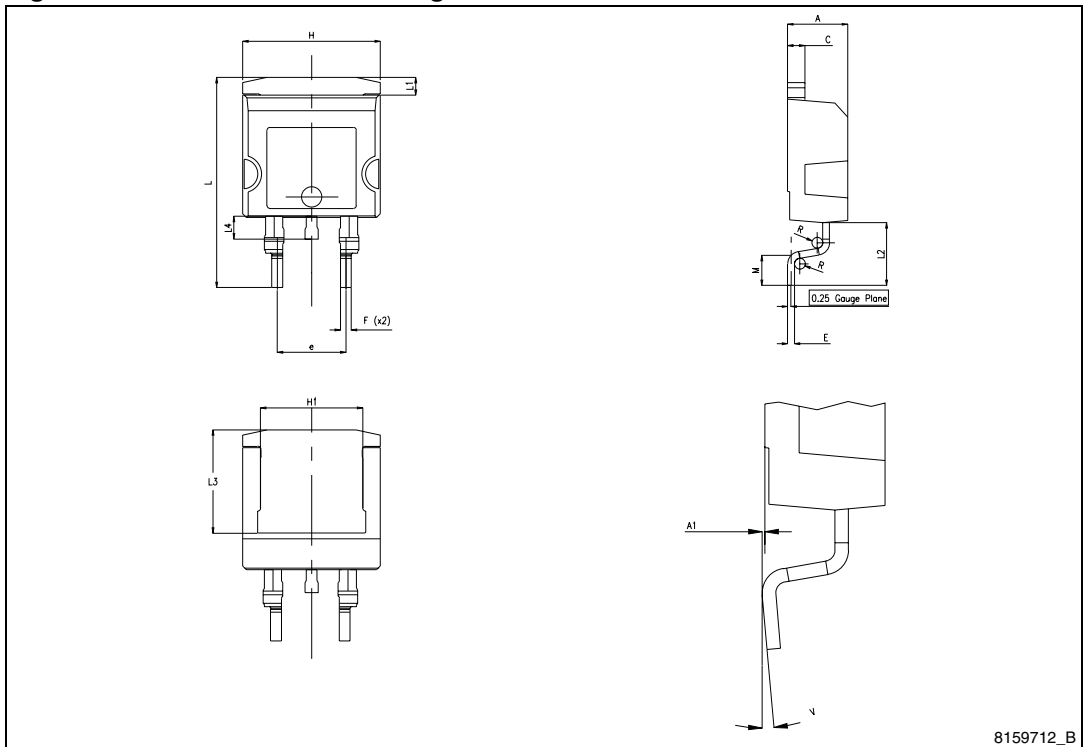
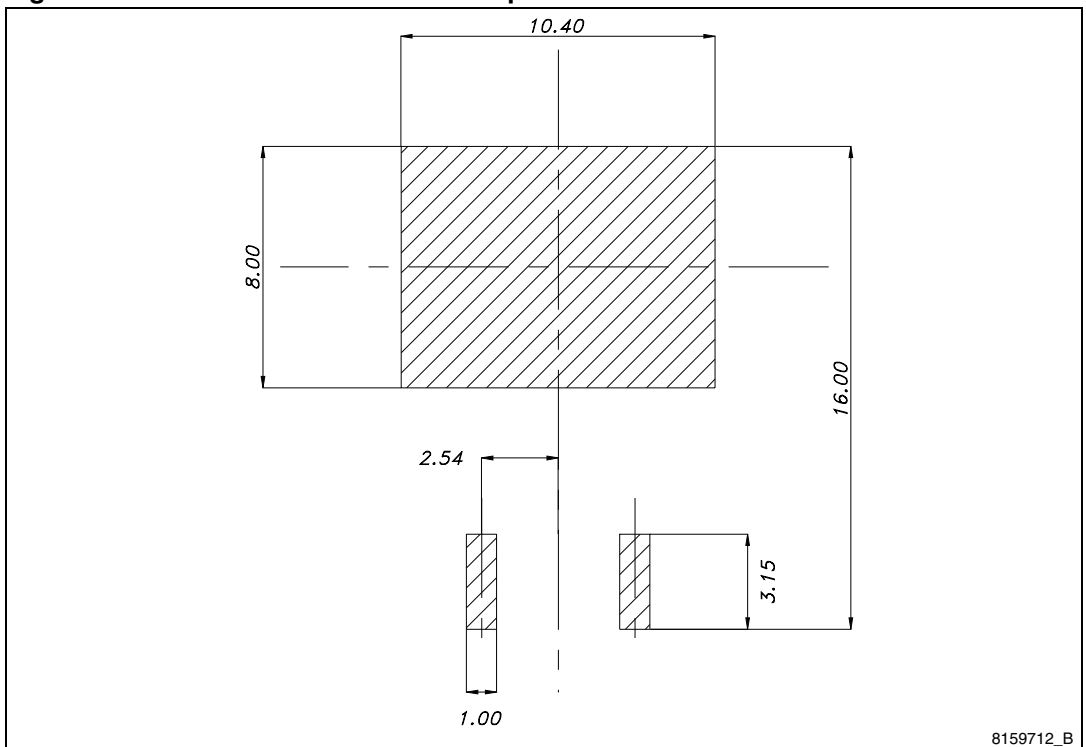
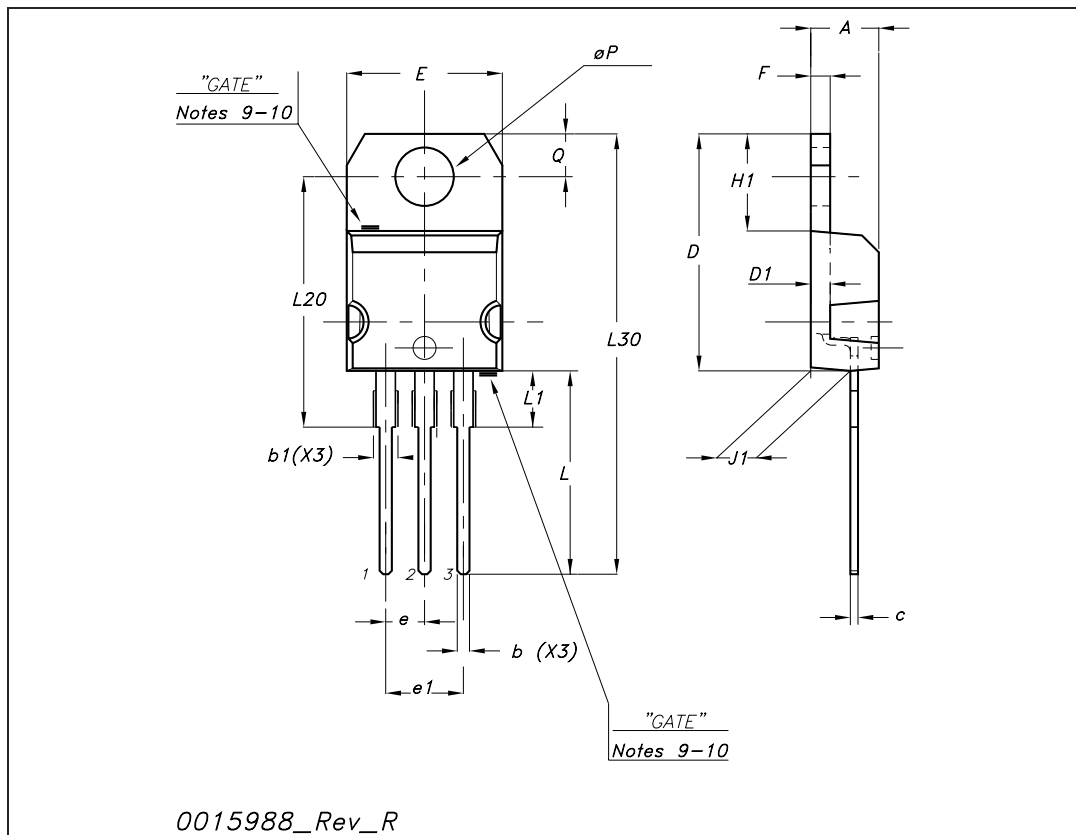


Figure 9. H²PAK 2 recommended footprint



TO-220 mechanical data

Dim	mm			inch		
	Min	Typ	Max	Min	Typ	Max
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
c	0.48		0.70	0.019		0.027
D	15.25		15.75	0.6		0.62
D1		1.27			0.050	
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.051
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
∅P	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



5 Revision history

Table 9. Document revision history

Date	Revision	Changes
15-Jun-2009	1	First release
15-Jul-2009	2	Document status promoted from target specification to preliminary data

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2009 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com